CLAIMS

1. A polishing pad mounted on a surface plate of a polishing device and used for a polishing process, characterized in that

the polishing pad has a plurality of foam cells and a plurality of communication holes that allow adjacent foam cells of the foam cells to communicate with each other, and

in a section of the polishing pad taken in a direction normal to the surface plate, the communication holes having a cross-sectional area of 0.01 mm^2 or more are present at a density of 30 or more communication holes per 25 mm^2 of the section.

2. The polishing pad according to claim 1, wherein

the surface plate of the polishing device includes an upper surface plate and a lower surface plate,

an upper-side polishing pad is attached to the upper surface plate,

a lower-side polishing pad is attached to the lower surface plate, and

the polishing pad is used as the lower-side polishing pad.

3. The polishing pad according to claim 1 or 2, wherein

an attraction force of at least the lower-side polishing pad of the polishing pad on a substrate is not less than 0.50g/cm^2 and not more than 15g/cm^2.

4. A method for manufacturing a glass substrate for an information recording medium using a polishing device in which a polishing pad composed of a member containing a plurality of foam cells is mounted on a surface plate, and a surface of a glass substrate is polished using the polishing pad, the method comprising the steps of:

placing the glass substrate on the surface plate;

polishing the surface of the glass substrate using the polishing device while supplying a liquid polishing agent to the glass substrate; and

removing the polished glass substrate from the surface plate, wherein

at least a lower-side polishing pad of the polishing pad has an open-cell structure in which a plurality of communication holes that allow adjacent foam cells of

the foam cells to communicate with each other are formed, and

in a section of the lower-side polishing pad taken in a direction of a normal to the surface plate, the communication holes having a cross-sectional area of 0.01 mm^2 or more are present at a density of 30 or more communication holes per 25 mm^2.

5. The method for manufacturing a glass substrate for an information recording medium according to claim 4, wherein

in the section of the lower-side polishing pad taken in the direction of the normal to the surface plate, the communication holes having a cross-sectional area of 0.01 mm^2 or more are present at a density of 80 or more communication holes per 25 mm^2.

6. The method for manufacturing a glass substrate for an information recording medium according to claim 4 or 5, wherein

in the step of removing the polished glass substrate from the surface plate, the polished glass substrate is removed from the surface plate in a state in which the polishing pad still contains the liquid polishing agent.

7. The method for manufacturing a glass substrate for an information recording medium according to claim 6, wherein

in the step of removing the polished glass substrate from the surface plate, the liquid polishing agent has a concentration that is 1.5-fold or more when compared with a concentration of the liquid polishing agent in the step of polishing the surface of the glass substrate using the polishing device.

8. A polishing device comprising a polishing pad as recited in any one of claims 1 to 3 mounted on a surface plate.